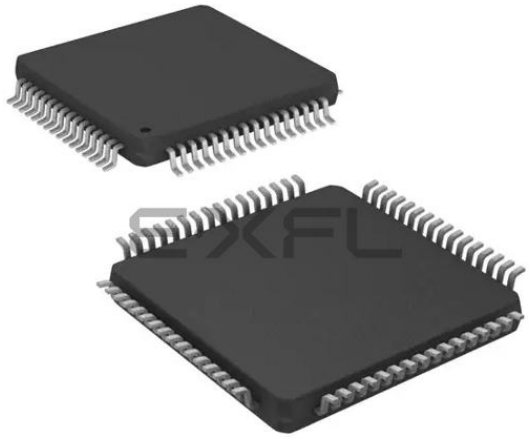
Microchip Technology - DSPIC30F6015-30I/PT Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	30 MIPs
Connectivity	CANbus, I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, Motor Control PWM, QEI, POR, PWM, WDT
Number of I/O	52
Program Memory Size	144KB (48K x 24)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic30f6015-30i-pt

NOTES:

TABLE 1-1: dsPIC30F6010A/6015 I/O PIN DESCRIPTIONS (CONTINUED)

Pin Name	Pin Type	Buffer Type	Description
U1RX	I	ST	UART1 Receive.
U1TX	O	—	UART1 Transmit.
U1ARX	I	ST	UART1 Alternate Receive.
U1ATX	O	—	UART1 Alternate Transmit.
U2RX	I	ST	UART2 Receive.
U2TX	O	—	UART2 Transmit.
VDD	P	—	Positive supply for logic and I/O pins.
VSS	P	—	Ground reference for logic and I/O pins.
VREF+	I	Analog	Analog Voltage Reference (High) input.
VREF-	I	Analog	Analog Voltage Reference (Low) input.

Legend: CMOS = CMOS compatible input or output Analog = Analog input
ST = Schmitt Trigger input with CMOS levels O = Output
I = Input P = Power

2.4.1 MULTIPLIER

The 17x17-bit multiplier is capable of signed or unsigned operations and can multiplex its output using a scaler to support either 1.31 fractional (Q31) or 32-bit integer results. Unsigned operands are zero-extended into the 17th bit of the multiplier input value. Signed operands are sign-extended into the 17th bit of the multiplier input value. The output of the 17x17-bit multiplier/scaler is a 33-bit value, which is sign-extended to 40 bits. Integer data is inherently represented as a signed two's complement value, where the MSB is defined as a sign bit. Generally speaking, the range of an N-bit two's complement integer is -2^{N-1} to $2^{N-1} - 1$. For a 16-bit integer, the data range is -32768 (0x8000) to 32767 (0x7FFF), including 0. For a 32-bit integer, the data range is -2,147,483,648 (0x8000 0000) to 2,147,483,645 (0x7FFF FFFF).

When the multiplier is configured for fractional multiplication, the data is represented as a two's complement fraction, where the MSB is defined as a sign bit and the radix point is implied to lie just after the sign bit (QX format). The range of an N-bit two's complement fraction with this implied radix point is -1.0 to $(1-2^{1-N})$. For a 16-bit fraction, the Q15 data range is -1.0 (0x8000) to 0.999969482 (0x7FFF), including 0 and has a precision of 3.01518×10^{-5}. In Fractional mode, a 16x16 multiply operation generates a 1.31 product, which has a precision of 4.65661×10^{-10}.

The same multiplier is used to support the MCU multiply instructions, which include integer 16-bit signed, unsigned and mixed sign multiplies.

The MUL instruction may be directed to use byte or word-sized operands. Byte operands will direct a 16-bit result, and word operands will direct a 32-bit result to the specified register(s) in the W array.

2.4.2 DATA ACCUMULATORS AND ADDER/SUBTRACTOR

The data accumulator consists of a 40-bit adder/subtractor with automatic sign extension logic. It can select one of two accumulators (A or B) as its pre-accumulation source and post-accumulation destination. For the ADD and LAC instructions, the data to be accumulated or loaded can be optionally scaled via the barrel shifter, prior to accumulation.

2.4.2.1 Adder/Subtractor, Overflow and Saturation

The adder/subtractor is a 40-bit adder with an optional zero input into one side and either true or complement data into the other input. In the case of addition, the carry/borrow input is active-high and the other input is true data (not complemented), whereas in the case of subtraction, the carry/borrow input is active-low and the other input is complemented. The adder/subtractor generates Overflow Status bits, SA/SB and OA/OB, which are latched and reflected in the STATUS register.

- Overflow from bit 39: this is a catastrophic overflow in which the sign of the accumulator is destroyed.
- Overflow into guard bits 32 through 39: this is a recoverable overflow. This bit is set whenever all the guard bits are not identical to each other.

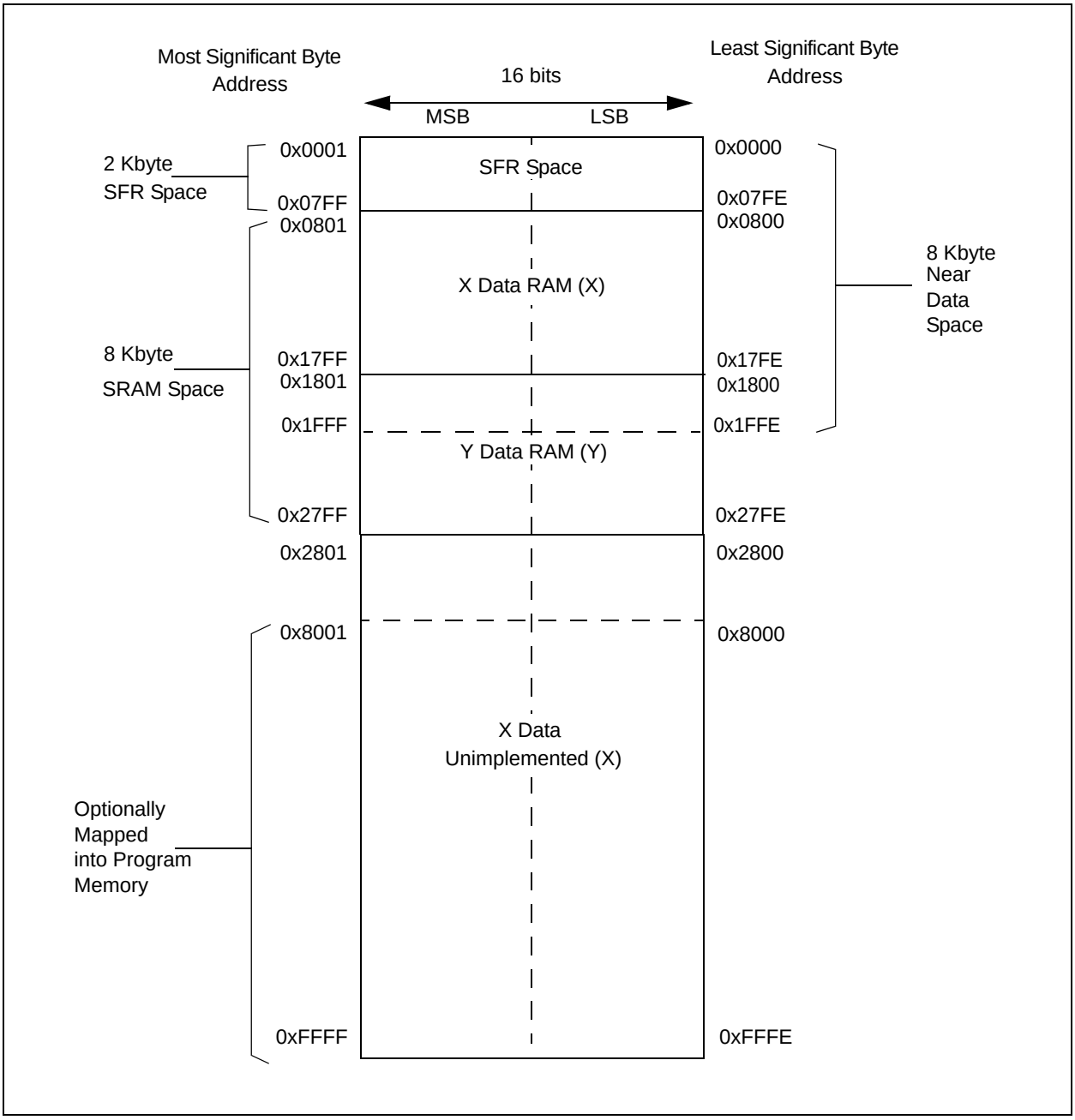
The adder has an additional saturation block which controls accumulator data saturation, if selected. It uses the result of the adder, the Overflow Status bits described above, and the SATA/B (CORCON<7:6>) and ACCSAT (CORCON<4>) mode control bits to determine when and to what value to saturate.

Six STATUS register bits have been provided to support saturation and overflow. They are:

1. OA:
   AccA overflowed into guard bits
2. OB:
   AccB overflowed into guard bits
3. SA:
   AccA saturated (bit 31 overflow and saturation)
   or
   AccA overflowed into guard bits and saturated (bit 39 overflow and saturation)
4. SB:
   AccB saturated (bit 31 overflow and saturation)
   or
   AccB overflowed into guard bits and saturated (bit 39 overflow and saturation)
5. OAB:
   Logical OR of OA and OB
6. SAB:
   Logical OR of SA and SB

The OA and OB bits are modified each time data passes through the adder/subtractor. When set, they indicate that the most recent operation has overflowed into the accumulator guard bits (bits 32 through 39). The OA and OB bits can also optionally generate an arithmetic warning trap when set and the corresponding overflow trap flag enable bit (OVATE, OVBTE) in the INTCON1 register (refer to **Section 5.0 "Interrupts"**) is set. This allows the user to take immediate action, for example, to correct system gain.

FIGURE 3-6: dsPIC30F6010A/6015 DATA SPACE MEMORY MAP



6.4 RTSP Operation

The dsPIC30F Flash program memory is organized into rows and panels. Each row consists of 32 instructions, or 96 bytes. Each panel consists of 128 rows, or 4K x 24 instructions. RTSP allows the user to erase one row (32 instructions) at a time and to program 32 instructions at one time.

Each panel of program memory contains write latches that hold 32 instructions of programming data. Prior to the actual programming operation, the write data must be loaded into the panel write latches. The data to be programmed into the panel is loaded in sequential order into the write latches; instruction 0, instruction 1, etc. The addresses loaded must always be from a 32 address boundary.

The basic sequence for RTSP programming is to set up a Table Pointer, then do a series of TBLWT instructions to load the write latches. Programming is performed by setting the special bits in the NVMCON register. 32 TBLWTL and 32 TBLWTH instructions are required to load the 32 instructions.

All of the table write operations are single-word writes (2 instruction cycles), because only the table latches are written.

After the latches are written, a programming operation needs to be initiated to program the data.

The Flash program memory is readable, writable and erasable during normal operation over the entire V_{DD} range.

6.5 RTSP Control Registers

The four SFRs used to read and write the program Flash memory are:

- NVMCON
- NVMADR
- NVMADRU
- NVMKEY

6.5.1 NVMCON REGISTER

The NVMCON register controls which blocks are to be erased, which memory type is to be programmed and start of the programming cycle.

6.5.2 NVMADR REGISTER

The NVMADR register is used to hold the lower two bytes of the Effective Address. The NVMADR register captures the EA<15:0> of the last table instruction that has been executed and selects the row to write.

6.5.3 NVMADRU REGISTER

The NVMADRU register is used to hold the upper byte of the Effective Address. The NVMADRU register captures the EA<23:16> of the last table instruction that has been executed.

6.5.4 NVMKEY REGISTER

NVMKEY is a write-only register that is used for write protection. To start a programming or an erase sequence, the user must consecutively write 0x55 and 0xAA to the NVMKEY register. Refer to **Section 6.6 "Programming Operations"** for further details.

Note:	The user can also directly write to the NVMADR and NVMADRU registers to specify a program memory address for erasing or programming.

7.3.2 WRITING A BLOCK OF DATA EEPROM

To write a block of data EEPROM, write to all sixteen latches first, then set the NVMCON register and program the block.

EXAMPLE 7-5: DATA EEPROM BLOCK WRITE

```
    MOV        #LOW_ADDR_WORD,W0  ; Init pointer
    MOV        #HIGH_ADDR_WORD,W1
    MOV        W1,TBLPAG
    MOV        #data1,W2          ; Get 1st data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data2,W2          ; Get 2nd data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data3,W2          ; Get 3rd data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data4,W2          ; Get 4th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data5,W2          ; Get 5th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data6,W2          ; Get 6th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data7,W2          ; Get 7th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data8,W2          ; Get 8th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data9,W2          ; Get 9th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data10,W2         ; Get 10th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data11,W2         ; Get 11th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data12,W2         ; Get 12th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data13,W2         ; Get 13th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data14,W2         ; Get 14th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data15,W2         ; Get 15th data
    TBLWTL     W2,[W0]++          ; write data
    MOV        #data16,W2         ; Get 16th data
    TBLWTL     W2,[W0]++          ; write data. The NVMADR captures last table access address.
    MOV        #0x400A,W0         ; Select data EEPROM for multi word op
    MOV        W0,NVMCON          ; Operate Key to allow program operation
    DISI       #5                 ; Block all interrupts with priority <7
                                  ; for next 5 instructions
    MOV        #0x55,W0
    MOV        W0,NVMKEY          ; Write the 0x55 key
    MOV        #0xAA,W1
    MOV        W1,NVMKEY          ; Write the 0xAA key
    BSET       NVMCON,#WR         ; Start write cycle
    NOP
    NOP
```

7.4 Write Verify

Depending on the application, good programming practice may dictate that the value written to the memory should be verified against the original value. This should be used in applications where excessive writes can stress bits near the specification limit.

7.5 Protection Against Spurious Write

There are conditions when the device may not want to write to the data EEPROM memory. To protect against spurious EEPROM writes, various mechanisms have been built-in. On power-up, the WREN bit is cleared; also, the Power-up Timer prevents EEPROM write.

The write initiate sequence and the WREN bit together, help prevent an accidental write during brown-out, power glitch or software malfunction.

13.1 Timer2 and Timer3 Selection Mode

Each output compare channel can select between one of two 16-bit timers; Timer2 or Timer3.

The selection of the timers is controlled by the OCTSEL bit (OCxCON<3>). Timer2 is the default timer resource for the Output Compare module.

13.2 Simple Output Compare Match Mode

When control bits OCM<2:0> (OCxCON<2:0>) = 001, 010 or 011, the selected output compare channel is configured for one of three simple output compare match modes:

- Compare forces I/O pin low
- Compare forces I/O pin high
- Compare toggles I/O pin

The OCxR register is used in these modes. The OCxR register is loaded with a value and is compared to the selected incrementing timer count. When a compare occurs, one of these compare match modes occurs. If the counter resets to zero before reaching the value in OCxR, the state of the OCx pin remains unchanged.

13.3 Dual Output Compare Match Mode

When control bits OCM<2:0> (OCxCON<2:0>) = 100 or 101, the selected output compare channel is configured for one of two Dual Output Compare modes, which are:

- Single Output Pulse mode
- Continuous Output Pulse mode

13.3.1 SINGLE PULSE MODE

For the user to configure the module for the generation of a single output pulse, the following steps are required (assuming timer is off):

- Determine instruction cycle time TCY.
- Calculate desired pulse-width value based on TCY.
- Calculate time to start pulse from timer start value of 0x0000.
- Write pulse-width start and stop times into OCxR and OCxRS Compare registers (x denotes channel 1, 2, ...,N).
- Set Timer Period register to value equal to, or greater than, value in OCxRS Compare register.
- Set OCM<2:0> = 100.
- Enable timer, TON (TxCON<15>) = 1.

To initiate another single pulse, issue another write to set OCM<2:0> = 100.

13.3.2 CONTINUOUS PULSE MODE

For the user to configure the module for the generation of a continuous stream of output pulses, the following steps are required:

- Determine instruction cycle time TCY.
- Calculate desired pulse value based on TCY.
- Calculate timer to start pulse width from timer start value of 0x0000.
- Write pulse-width start and stop times into OCxR and OCxRS (x denotes channel 1, 2, ...,N) Compare registers, respectively.
- Set Timer Period register to value equal to, or greater than, value in OCxRS Compare register.
- Set OCM<2:0> = 101.
- Enable timer, TON (TxCON<15>) = 1.

13.4 Simple PWM Mode

When control bits OCM<2:0> (OCxCON<2:0>) = 110 or 111, the selected output compare channel is configured for the PWM mode of operation. When configured for the PWM mode of operation, OCxR is the main latch (read-only) and OCxRS is the secondary latch. This enables glitchless PWM transitions.

The user must perform the following steps in order to configure the output compare module for PWM operation:

1. Set the PWM period by writing to the appropriate period register.
2. Set the PWM duty cycle by writing to the OCxRS register.
3. Configure the output compare module for PWM operation.
4. Set the TMRx prescale value and enable the Timer, TON (TxCON<15>) = 1.

13.4.1 INPUT PIN FAULT PROTECTION FOR PWM

When control bits OCM<2:0> (OCxCON<2:0>) = 111, the selected output compare channel is again configured for the PWM mode of operation, with the additional feature of input Fault protection. While in this mode, if a logic '0' is detected on the OCFA/B pin, the respective PWM output pin is placed in the high-impedance input state. The OCFLT bit (OCxCON<4>) indicates whether a Fault condition has occurred. This state will be maintained until both of the following events have occurred:

- The external Fault condition has been removed.
- The PWM mode has been re-enabled by writing to the appropriate control bits.

14.4 Programmable Digital Noise Filters

The digital noise filter section is responsible for rejecting noise on the incoming quadrature signals. Schmitt Trigger inputs and a three-clock cycle delay filter combine to reject low level noise and large, short duration noise spikes that typically occur in noise prone applications, such as a motor system.

The filter ensures that the filtered output signal is not permitted to change until a stable value has been registered for three consecutive clock cycles.

For the QEA, QEB and INDX pins, the clock divide frequency for the digital filter is programmed by bits QECK<2:0> (DFLTCON<6:4>) and are derived from the base instruction cycle TCY.

To enable the filter output for channels QEA, QEB and INDX, the QEOUT bit must be '1'. The filter network for all channels is disabled on POR and BOR.

14.5 Alternate 16-bit Timer/Counter

When the QEI module is not configured for the QEI mode QEIM<2:0> = 001, the module can be configured as a simple 16-bit timer/counter. The setup and control of the auxiliary timer is accomplished through the QEICON SFR register. This timer functions identically to Timer1. The QEA pin is used as the timer clock input.

When configured as a timer, the POSCNT register serves as the Timer Count register and the MAXCNT register serves as the Period register. When a Timer/Period register match occur, the QEI interrupt flag will be asserted.

The only exception between the general purpose timers and this timer is the added feature of external up/down input select. When the UPDN pin is asserted high, the timer will increment up. When the UPDN pin is asserted low, the timer will be decremented.

Note:	Changing the operational mode (i.e., from QEI to Timer or vice versa), will not affect the Timer/Position Count register contents.

The UPDN control/Status bit (QEICON<11>) can be used to select the count direction state of the Timer register. When UPDN = 1, the timer will count up. When UPDN = 0, the timer will count down.

In addition, control bit, UDSRC (QEICON<0>), determines whether the timer count direction state is based on the logic state, written into the UPDN control/Status bit (QEICON<11>), or the QEB pin state. When UDSRC = 1, the timer count direction is controlled from the QEB pin. Likewise, when UDSRC = 0, the timer count direction is controlled by the UPDN bit.

Note:	This Timer does not support the External Asynchronous Counter mode of operation. If using an external clock source, the clock will automatically be synchronized to the internal instruction cycle.

14.6 QEI Module Operation During CPU Sleep Mode

14.6.1 QEI OPERATION DURING CPU SLEEP MODE

The QEI module will be halted during the CPU Sleep mode.

14.6.2 TIMER OPERATION DURING CPU SLEEP MODE

During CPU Sleep mode, the timer will not operate, because the internal clocks are disabled.

14.7 QEI Module Operation During CPU Idle Mode

Since the QEI module can function as a Quadrature Encoder Interface, or as a 16-bit timer, the following section describes operation of the module in both modes.

14.7.1 QEI OPERATION DURING CPU IDLE MODE

When the CPU is placed in the Idle mode, the QEI module will operate if the QEISIDL bit (QEICON<13>) = 0. This bit defaults to a logic '0' upon executing POR and BOR. For halting the QEI module during the CPU Idle mode, QEISIDL should be set to '1'.

15.6 Complementary PWM Operation

In the Complementary mode of operation, each pair of PWM outputs is obtained by a complementary PWM signal. A dead time may be optionally inserted during device switching, when both outputs are inactive for a short period (Refer to **Section 15.7 "Dead-Time Generators"**).

In Complementary mode, the duty cycle comparison units are assigned to the PWM outputs as follows:

- PDC1 register controls PWM1H/PWM1L outputs
- PDC2 register controls PWM2H/PWM2L outputs
- PDC3 register controls PWM3H/PWM3L outputs
- PDC4 register controls PWM4H/PWM4L outputs

The Complementary mode is selected for each PWM I/O pin pair by clearing the appropriate PMODx bit in the PWMCON1 SFR. The PWM I/O pins are set to Complementary mode by default upon a device Reset.

15.7 Dead-Time Generators

Dead-time generation may be provided when any of the PWM I/O pin pairs are operating in the Complementary Output mode. The PWM outputs use Push-Pull drive circuits. Due to the inability of the power output devices to switch instantaneously, some amount of time must be provided between the turn off event of one PWM output in a complementary pair and the turn on event of the other transistor.

The PWM module allows two different dead times to be programmed. These two dead times may be used in one of two methods described below to increase user flexibility:

- The PWM output signals can be optimized for different turn off times in the high side and low side transistors in a complementary pair of transistors. The first dead time is inserted between the turn off event of the lower transistor of the complementary pair and the turn on event of the upper transistor. The second dead time is inserted between the turn off event of the upper transistor and the turn on event of the lower transistor.
- The two dead times can be assigned to individual PWM I/O pin pairs. This Operating mode allows the PWM module to drive different transistor/load combinations with each complementary PWM I/O pin pair.

15.7.1 DEAD-TIME GENERATORS

Each complementary output pair for the PWM module has a 6-bit down counter that is used to produce the dead-time insertion. As shown in Figure 15-4, each dead-time unit has a rising and falling edge detector connected to the duty cycle comparison output.

15.7.2 DEAD-TIME ASSIGNMENT

The DTCON2 SFR contains control bits that allow the dead times to be assigned to each of the complementary outputs. Table 15-1 summarizes the function of each dead-time selection control bit.

TABLE 15-1: DEAD-TIME SELECTION BITS

Bit	Selects
DTS1A	PWM1L/PWM1H active edge dead time.
DTS1I	PWM1L/PWM1H inactive edge dead time.
DTS2A	PWM2L/PWM2H active edge dead time.
DTS2I	PWM2L/PWM2H inactive edge dead time.
DTS3A	PWM3L/PWM3H active edge dead time.
DTS3I	PWM3L/PWM3H inactive edge dead time.
DTS4A	PWM4L/PWM4H active edge dead time.
DTS4I	PWM4L/PWM4H inactive edge dead time.

15.7.3 DEAD-TIME RANGES

The amount of dead time provided by each dead-time unit is selected by specifying the input clock prescaler value and a 6-bit unsigned value. The amount of dead time provided by each unit may be set independently.

Four input clock prescaler selections have been provided to allow a suitable range of dead times, based on the device operating frequency. The clock prescaler option may be selected independently for each of the two dead-time values. The dead-time clock prescaler values are selected using the DTAPS<1:0> and DTBPS<1:0> control bits in the DTCON1 SFR. One of four clock prescaler options (T_{CY}, 2 T_{CY}, 4 T_{CY} or 8 T_{CY}) may be selected for each of the dead-time values.

After the prescaler values are selected, the dead time for each unit is adjusted by loading two 6-bit unsigned values into the DTCON1 SFR.

The dead-time unit prescalers are cleared on the following events:

- On a load of the down timer due to a duty cycle comparison edge event.
- On a write to the DTCON1 or DTCON2 registers.
- On any device Reset.

Note:	The user should not modify the DTCON1 or DTCON2 values while the PWM module is operating (PTEN = 1). Unexpected results may occur.

20.1 A/D Result Buffer

The module contains a 16-word dual port, read-only buffer, called ADCBUF0...ADCBUFF, to buffer the A/D results. The RAM is 10-bits wide, but is read into different format 16-bit words. The contents of the sixteen A/D Conversion Result Buffer registers, ADCBUF0 through ADCBUFF, cannot be written by user software.

20.2 Conversion Operation

After the A/D module has been configured, the sample acquisition is started by setting the SAMP bit. Various sources, such as a programmable bit, timer time-outs and external events, will terminate acquisition and start a conversion. When the A/D conversion is complete, the result is loaded into ADCBUF0...ADCBUFF, and the A/D Interrupt Flag ADIF and the DONE bit are set after the number of samples specified by the SMPI bit.

The following steps should be followed for doing an A/D conversion:

1. Configure the A/D module:
   - Configure analog pins, voltage reference and digital I/O
   - Select A/D input channels
   - Select A/D conversion clock
   - Select A/D conversion trigger
   - Turn on A/D module
2. Configure A/D interrupt (if required):
   - Clear ADIF bit
   - Select A/D interrupt priority
3. Start sampling.
4. Wait the required acquisition time.
5. Trigger acquisition end, start conversion
6. Wait for A/D conversion to complete, by either:
   - Waiting for the A/D interrupt
7. Read A/D result buffer, clear ADIF if required.

20.3 Selecting the Conversion Sequence

Several groups of control bits select the sequence in which the A/D connects inputs to the sample/hold channels, converts channels, writes the buffer memory, and generates interrupts. The sequence is controlled by the sampling clocks.

The SIMSAM bit controls the acquire/convert sequence for multiple channels. If the SIMSAM bit is '0', the two or four selected channels are acquired and converted sequentially, with two or four sample clocks. If the SIMSAM bit is '1', two or four selected channels are acquired simultaneously, with one sample clock. The channels are then converted sequentially. Obviously, if there is only 1 channel selected, the SIMSAM bit is not applicable.

The CHPS bits selects how many channels are sampled. This can vary from 1, 2 or 4 channels. If CHPS selects 1 channel, the CH0 channel will be sampled at the sample clock and converted. The result is stored in the buffer. If CHPS selects 2 channels, the CH0 and CH1 channels will be sampled and converted. If CHPS selects 4 channels, the CH0, CH1, CH2 and CH3 channels will be sampled and converted.

The SMPI bits select the number of acquisition/conversion sequences that would be performed before an interrupt occurs. This can vary from 1 sample per interrupt to 16 samples per interrupt.

The user cannot program a combination of CHPS and SMPI bits that specifies more than 16 conversions per interrupt, or 8 conversions per interrupt, depending on the BUFM bit. The BUFM bit, when set, will split the 16-word results buffer (ADCBUF0...ADCBUFF) into two 8-word groups. Writing to the 8-word buffers will be alternated on each interrupt event. Use of the BUFM bit will depend on how much time is available for moving data out of the buffers after the interrupt, as determined by the application.

If the processor can quickly unload a full buffer within the time it takes to acquire and convert one channel, the BUFM bit can be '0' and up to 16 conversions may be done per interrupt. The processor will have one sample and conversion time to move the sixteen conversions.

If the processor cannot unload the buffer within the acquisition and conversion time, the BUFM bit should be '1'. For example, if SMPI<3:0> (ADCON2<5:2> = 0111), then eight conversions will be loaded into 1/2 of the buffer, following which an interrupt occurs. The next eight conversions will be loaded into the other 1/2 of the buffer. The processor will have the entire time between interrupts to move the eight conversions.

The ALTS bit can be used to alternate the inputs selected during the sampling sequence. The input multiplexer has two sets of sample inputs: MUX A and MUX B. If the ALTS bit is '0', only the MUX A inputs are selected for sampling. If the ALTS bit is '1' and SMPI<3:0> = 0000, on the first sample/convert sequence, the MUX A inputs are selected, and on the next acquire/convert sequence, the MUX B inputs are selected.

The CSCNA bit (ADCON2<10>) will allow the CH0 channel inputs to be alternately scanned across a selected number of analog inputs for the MUX A group. The inputs are selected by the ADCSSL register. If a particular bit in the ADCSSL register is '1', the corresponding input is selected. The inputs are always scanned from lower to higher numbered inputs, starting after each interrupt. If the number of inputs selected is greater than the number of samples taken per interrupt, the higher numbered inputs are unused.

Most single-word instructions are executed in a single instruction cycle, unless a conditional test is true or the program counter is changed as a result of the instruction. In these cases, the execution takes two instruction cycles with the additional instruction cycle(s) executed as a NOP. Notable exceptions are the BRA (unconditional/computed branch), indirect CALL/GOTO, all table reads and writes and RETURN/RETFIE instructions, which are single-word instructions, but take two or three cycles. Certain instructions that involve skipping over the subsequent instruction, require either two or three cycles if the skip is performed, depending on whether the instruction being skipped is a single-word or two-word instruction. Moreover, double word moves require two cycles. The double word instructions execute in two instruction cycles.

Note: For more details on the instruction set, refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157).

TABLE 22-1: SYMBOLS USED IN OPCODE DESCRIPTIONS

Field	Description
#text	Means literal defined by "text"
(text)	Means "content of text"
[text]	Means "the location addressed by text"
{ }	Optional field or operation
<n:m>	Register bit field
.b	Byte mode selection
.d	Double Word mode selection
.S	Shadow register select
.w	Word mode selection (default)
Acc	One of two accumulators {A, B}
AWB	Accumulator Write-Back Destination Address register ∈ {W13, [W13]+ = 2}
bit4	4-bit bit selection field (used in word addressed instructions) ∈ {0...15}
C, DC, N, OV, Z	MCU Status bits: Carry, Digit Carry, Negative, Overflow, Zero
Expr	Absolute address, label or expression (resolved by the linker)
f	File register address ∈ {0x0000...0x1FFF}
lit1	1-bit unsigned literal ∈ {0,1}
lit4	4-bit unsigned literal ∈ {0...15}
lit5	5-bit unsigned literal ∈ {0...31}
lit8	8-bit unsigned literal ∈ {0...255}
lit10	10-bit unsigned literal ∈ {0...255} for Byte mode, {0:1023} for Word mode
lit14	14-bit unsigned literal ∈ {0...16384}
lit16	16-bit unsigned literal ∈ {0...65535}
lit23	23-bit unsigned literal ∈ {0...8388608}; LSB must be '0'
None	Field does not require an entry, may be blank
OA, OB, SA, SB	DSP Status bits: AccA Overflow, AccB Overflow, AccA Saturate, AccB Saturate
PC	Program Counter
Slit10	10-bit signed literal ∈ {-512...511}
Slit16	16-bit signed literal ∈ {-32768...32767}
Slit6	6-bit signed literal ∈ {-16...16}

23.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

23.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, preprocessor, and one-step driver, and can run on multiple platforms.

23.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

23.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

23.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

TABLE 24-6: DC CHARACTERISTICS: OPERATING CURRENT (I_{DD})

DC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Operating Current (I_{DD})(2)						
DC31a	9.5	15	mA	25°C	3.3V	0.128 MIPS LPRC (512 kHz)
DC31b	9.5	15	mA	85°C		
DC31c	9.4	15	mA	125°C		
DC31e	18	27	mA	25°C	5V	
DC31f	17	27	mA	85°C		
DC31g	17	27	mA	125°C		
DC30a	15	23	mA	25°C	3.3V	(1.8 MIPS) FRC (7.37 MHz)
DC30b	15	23	mA	85°C		
DC30c	14	23	mA	125°C		
DC30e	30	45	mA	25°C	5V	
DC30f	29	45	mA	85°C		
DC30g	27	45	mA	125°C		
DC23a	40	50	mA	25°C	3.3V	4 MIPS
DC23b	40	50	mA	85°C		
DC23c	36	50	mA	125°C		
DC23e	44	64	mA	25°C	5V	
DC23f	43	64	mA	85°C		
DC23g	43	64	mA	125°C		
DC24a	50	75	mA	25°C	3.3V	10 MIPS
DC24b	51	75	mA	85°C		
DC24c	51	75	mA	125°C		
DC24e	85	125	mA	25°C	5V	
DC24f	84	125	mA	85°C		
DC24g	84	125	mA	125°C		
DC27a	89	115	mA	25°C	3.3V	20 MIPS
DC27b	89	115	mA	85°C		
DC27d	147	185	mA	25°C	5V	
DC27e	146	185	mA	85°C		
DC27f	145	185	mA	125°C		
DC29a	206	255	mA	25°C	5V	30 MIPS
DC29b	205	255	mA	85°C		

Note 1: Data in "Typical" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature also have an impact on the current consumption. The test conditions for all I_{DD} measurements are as follows: OSC1 driven with external square wave from rail-to-rail. All I/O pins are configured as Inputs and pulled to V_{DD}. $\overline{MCLR}$ = V_{DD}, WDT, FSCM, LVD and BOR are disabled. CPU, SRAM, Program Memory and Data Memory are operational. No peripheral modules are operating.

TABLE 24-15: PLL CLOCK TIMING SPECIFICATIONS (V_{DD} = 2.5 TO 5.5 V)

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
OS50	FPLLI	PLL Input Frequency Range(2)	4	—	10	MHz	EC with 4x PLL
			4	—	10	MHz	EC with 8x PLL
			4	—	7.5(4)	MHz	EC with 16x PLL
			4	—	10	MHz	XT with 4x PLL
			4	—	10	MHz	XT with 8x PLL
			4	—	7.5(4)	MHz	XT with 16x PLL
			5(3)	—	10	MHz	HS/2 with 4x PLL
			5(3)	—	10	MHz	HS/2 with 8x PLL
			5(3)	—	7.5(4)	MHz	HS/2 with 16x PLL
			4	—	8.33(3)	MHz	HS/3 with 4x PLL
			4	—	8.33(3)	MHz	HS/3 with 8x PLL
			4	—	7.5(4)	MHz	HS/3 with 16x PLL
OS51	FSYS	On-Chip PLL Output(2)	16	—	120	MHz	EC, XT, HS/2, HS/3 modes with PLL
OS52	TLOC	PLL Start-up Time (Lock Time)	—	20	50	µs	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: Limited by oscillator frequency range.

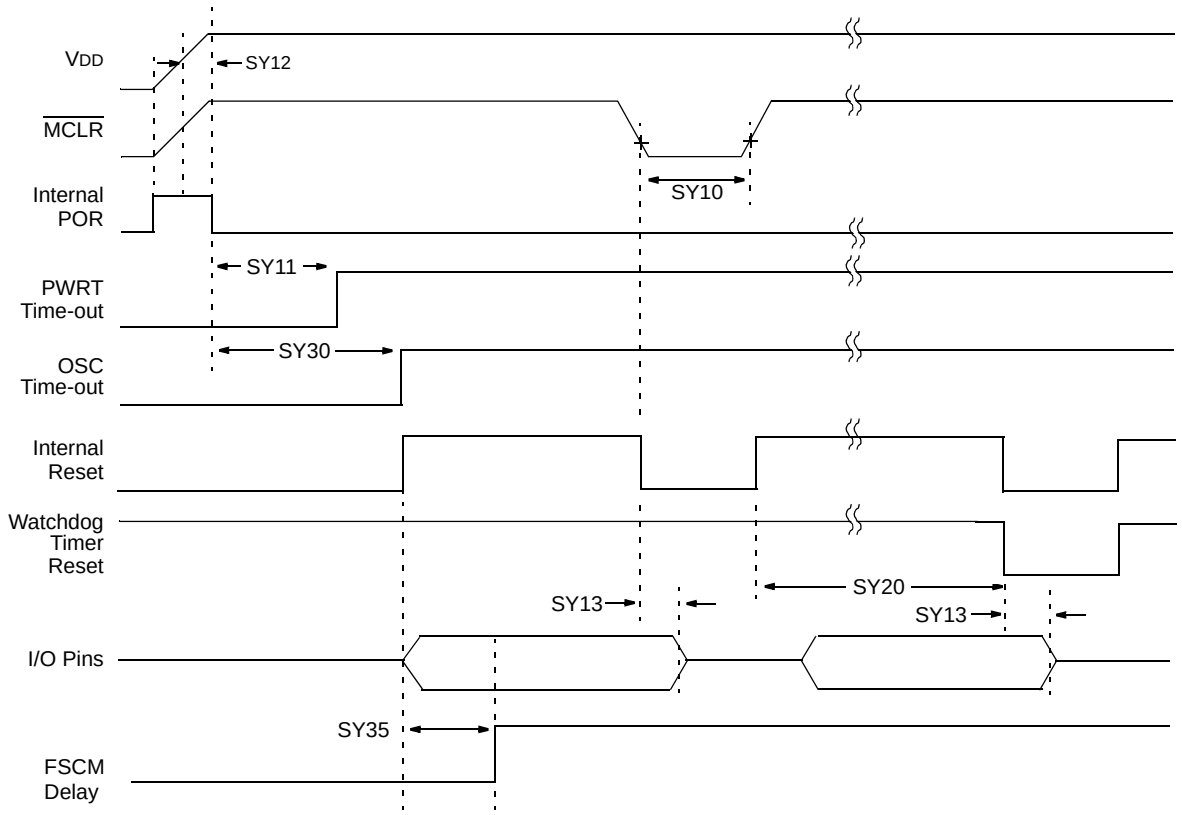
4: Limited by device operating frequency range.

TABLE 24-16: PLL JITTER

AC CHARACTERISTICS		Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**	
OS61	x4 PLL	—	0.251	0.413	%	-40°C ≤TA ≤+85°C	VDD = 3.0 to 3.6V
		—	0.251	0.413	%	-40°C ≤TA ≤+125°C	VDD = 3.0 to 3.6V
		—	0.256	0.47	%	-40°C ≤TA ≤+85°C	VDD = 4.5 to 5.5V
		—	0.256	0.47	%	-40°C ≤TA ≤+125°C	VDD = 4.5 to 5.5V
	x8 PLL	—	0.355	0.584	%	-40°C ≤TA ≤+85°C	VDD = 3.0 to 3.6V
		—	0.355	0.584	%	-40°C ≤TA ≤+125°C	VDD = 3.0 to 3.6V
		—	0.362	0.664	%	-40°C ≤TA ≤+85°C	VDD = 4.5 to 5.5V
		—	0.362	0.664	%	-40°C ≤TA ≤+125°C	VDD = 4.5 to 5.5V
	x16 PLL	—	0.67	0.92	%	-40°C ≤TA ≤+85°C	VDD = 3.0 to 3.6V
		—	0.632	0.956	%	-40°C ≤TA ≤+85°C	VDD = 4.5 to 5.5V
		—	0.632	0.956	%	-40°C ≤TA ≤+125°C	VDD = 4.5 to 5.5V

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 24-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING CHARACTERISTICS



Note: Refer to Figure 24-2 for load conditions.

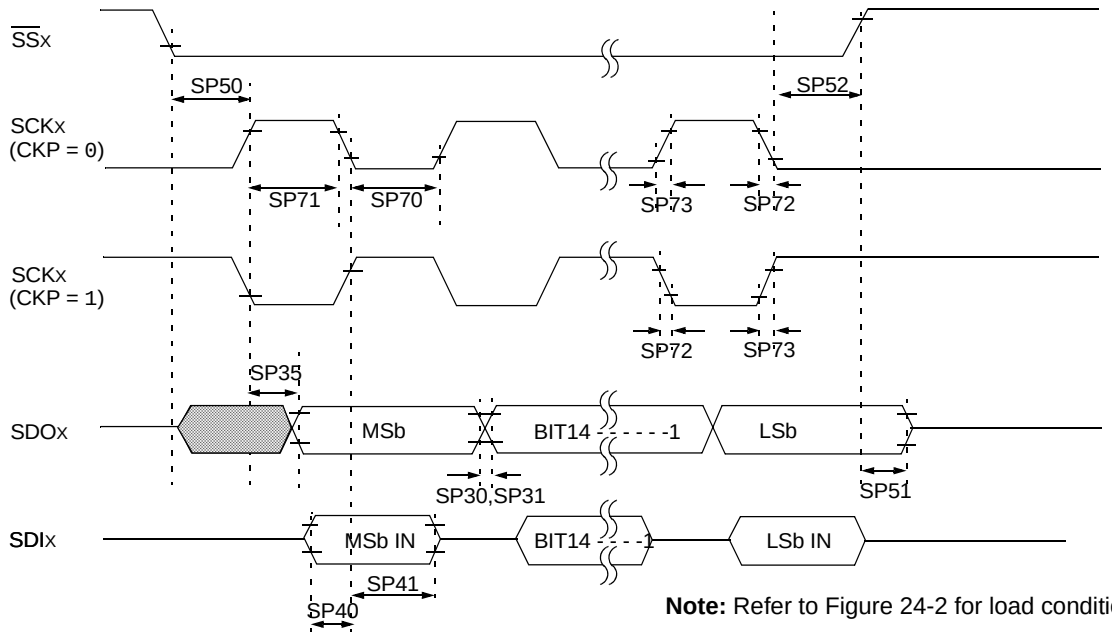
TABLE 24-24: TIMER2 AND TIMER4 EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
TB10	TtxH	TxCK High Time	Synchronous, no prescaler	0.5 TCY + 20	—	—	ns	Must also meet parameter TB15
			Synchronous, with prescaler	10	—	—	ns	
TB11	TtxL	TxCK Low Time	Synchronous, no prescaler	0.5 TCY + 20	—	—	ns	Must also meet parameter TB15
			Synchronous, with prescaler	10	—	—	ns	
TB15	TtxP	TxCK Input Period	Synchronous, no prescaler	TCY + 10	—	—	ns	N = prescale value (1, 8, 64, 256)
			Synchronous, with prescaler	Greater of: 20 ns or (TCY + 40)/N				
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.5 TCY	—	1.5 TCY	—	—

TABLE 24-25: TIMER3 AND TIMER5 EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
TC10	TtxH	TxCK High Time	Synchronous	0.5 TCY + 20	—	—	ns	Must also meet parameter TC15
TC11	TtxL	TxCK Low Time	Synchronous	0.5 TCY + 20	—	—	ns	Must also meet parameter TC15
TC15	TtxP	TxCK Input Period	Synchronous, no prescaler	TCY + 10	—	—	ns	N = prescale value (1, 8, 64, 256)
			Synchronous, with prescaler	Greater of: 20 ns or (TCY + 40)/N				
TC20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.5 TCY	—	1.5 TCY	—	—

FIGURE 24-18: SPI MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 24-2 for load conditions.

TABLE 24-35: SPI MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time	30	—	—	ns	—
SP71	TscH	SCKx Input High Time	30	—	—	ns	—
SP72	TscF	SCKx Input Fall Time(3)	—	10	25	ns	—
SP73	TscR	SCKx Input Rise Time(3)	—	10	25	ns	—
SP30	TdoF	SDOx Data Output Fall Time(3)	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time(3)	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	30	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SS}$x↓to SCKx↑ or SCKx↓Input	120	—	—	ns	—
SP51	TssH2doZ	$\overline{SS}$x↑ to SDOx Output High-impedance(3)	10	—	50	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SS}$x after SCK Edge	1.5 TCY +40	—	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: Assumes 50 pF load on all SPI pins.

TABLE 24-37: I²C™ BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min(1)**	**Max**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	—
IM20	TF:SCL	SDA and SCL Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDA and SCL Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	—	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	—	—	ns	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	After this period the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	—
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	—
			400 kHz mode	—	1000	ns	—
			1 MHz mode(2)	—	—	ns	—
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(2)	—	—	µs	
IM50	CB	Bus Capacitive Loading		—	400	pF	—

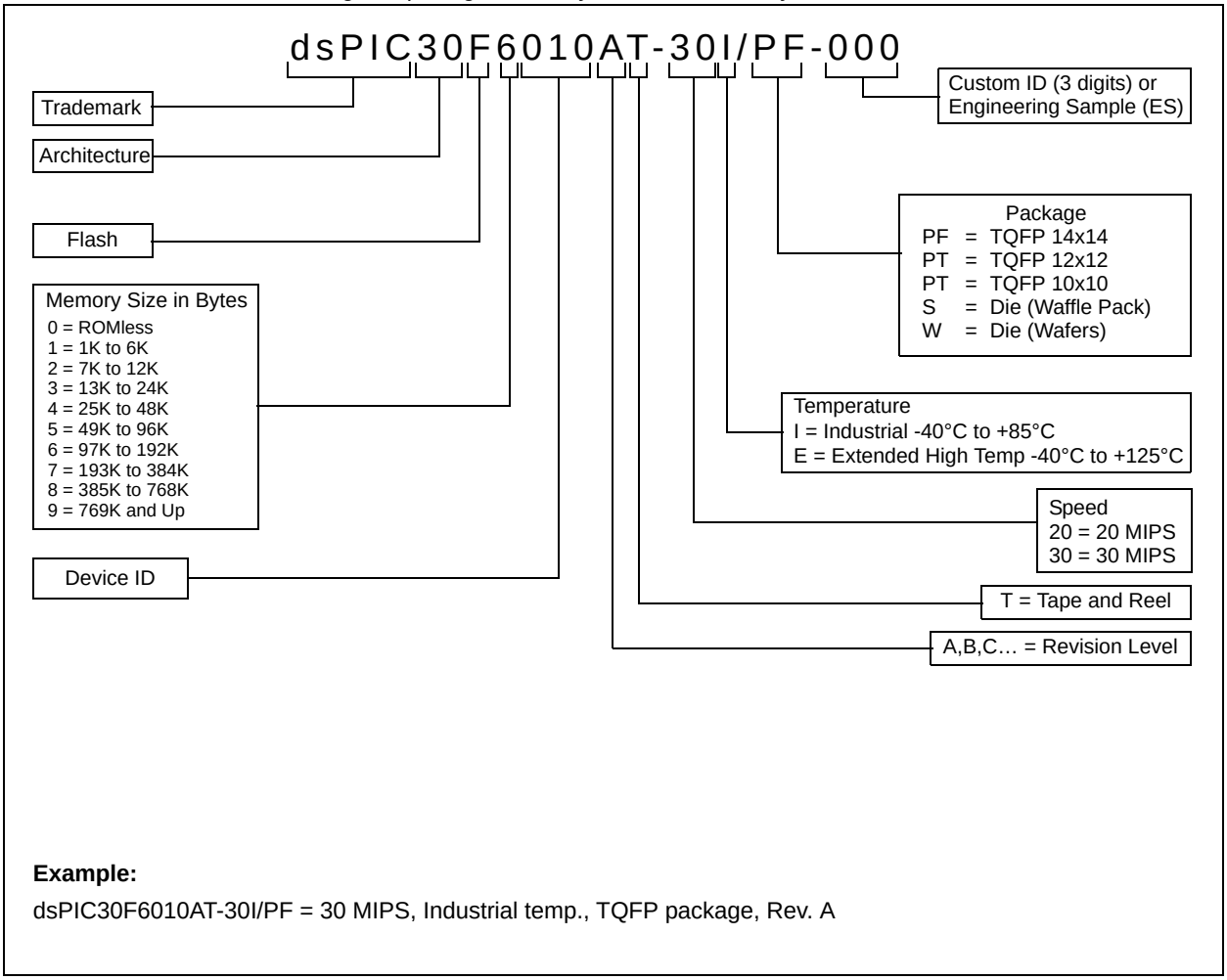
Note 1: BRG is the value of the I²C Baud Rate Generator. Refer to **Section 21. "Inter-Integrated Circuit (I²C™)"** (DS70046) in the "*dsPIC30F Family Reference Manual*".

2: Maximum pin capacitance = 10 pF for all I²C pins (for 1 MHz mode only).

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Example:

dsPIC30F6010AT-30I/PF = 30 MIPS, Industrial temp., TQFP package, Rev. A